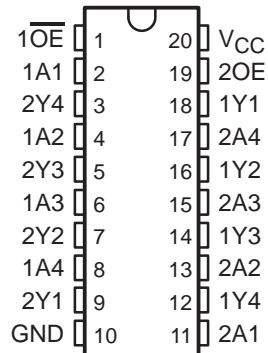


# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

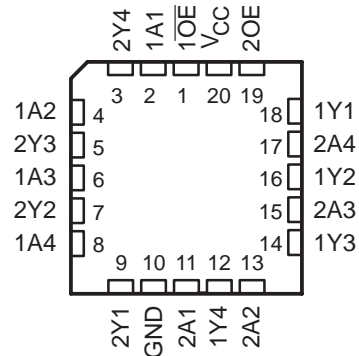
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 11$  ns
- $\pm 6$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

SN54HC241 ... J OR W PACKAGE  
SN74HC241 ... DW, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54HC241 ... FK PACKAGE  
(TOP VIEW)



## description/ordering information

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HC241 devices are organized as two 4-bit buffers/drivers with separate output-enable ( $1\overline{OE}$  and  $2OE$ ) inputs. When  $1\overline{OE}$  is low or  $2OE$  is high, the device passes noninverted data from the A inputs to the Y outputs. When  $1\overline{OE}$  is high or  $2OE$  is low, the outputs for the respective buffers/drivers are in the high-impedance state.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 20	SN74HC241N	SN74HC241N
	SOIC – DW	Tube of 25	SN74HC241DW	HC241
		Reel of 2000	SN74HC241DWR	
	SOP – NS	Reel of 2000	SN74HC241NSR	HC241
	TSSOP – PW	Reel of 70	SN74HC241PW	HC241
		Reel of 2000	SN74HC241PWR	
		Reel of 250	SN74HC241PWT	
-55°C to 125°C	CDIP – J	Tube of 20	SNJ54HC241J	SNJ54HC241J
	CFP – W	Tube of 85	SNJ54HC241W	SNJ54HC241W
	LCCC – FK	Tube of 55	SNJ54HC241FK	SNJ54HC241FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

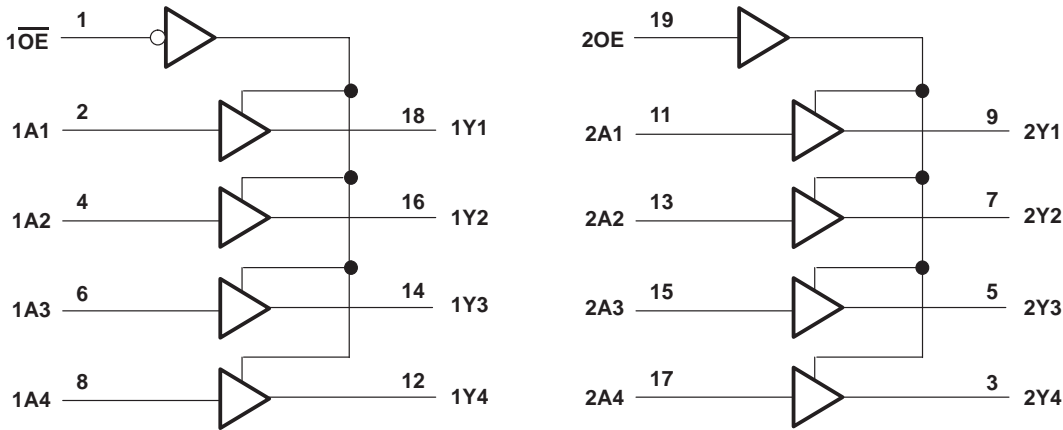
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FUNCTION TABLES

INPUTS		OUTPUT 1Y
1OE	1A	
L	H	H
L	L	L
H	X	Z

INPUTS		OUTPUT 2Y
2OE	2A	
H	H	H
H	L	L
L	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous current through $V_{CC}$ or GND	±70 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

# SN54HC241, SN74HC241

## OCTAL BUFFERS AND LINE DRIVERS

### WITH 3-STATE OUTPUTS

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#### recommended operating conditions (see Note 3)

			SN54HC241			SN74HC241			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage		2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5			1.5			V
		V <sub>CC</sub> = 4.5 V	3.15			3.15			
		V <sub>CC</sub> = 6 V	4.2			4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5			0.5			V
		V <sub>CC</sub> = 4.5 V	1.35			1.35			
		V <sub>CC</sub> = 6 V	1.8			1.8			
V <sub>I</sub>	Input voltage		0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
$\Delta t/\Delta v$	Input transition rise/fall time	V <sub>CC</sub> = 2 V	1000			1000			ns
		V <sub>CC</sub> = 4.5 V	500			500			
		V <sub>CC</sub> = 6 V	400			400			
T <sub>A</sub>	Operating free-air temperature		−55		125	−40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC241		SN74HC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = –20 $\mu$ A	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = –6 mA	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = –7.8 mA	6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 $\mu$ A	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100		±1000		±1000	nA
I <sub>OZ</sub>	V <sub>O</sub> = V <sub>CC</sub> or 0		6 V		±0.01	±0.5		±10		±5	$\mu$ A
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V			8		160		80	$\mu$ A
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF

# SN54HC241, SN74HC241

## OCTAL BUFFERS AND LINE DRIVERS

### WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC241		SN74HC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2 V		39	115		170		145	ns
			4.5 V		12	23		34		29	
			6 V		11	20		29		25	
$t_{en}$	$\overline{OE}$ or OE	Y	2 V		60	150		225		190	ns
			4.5 V		17	30		45		38	
			6 V		15	26		38		32	
$t_{dis}$	$\overline{OE}$ or OE	Y	2 V		40	150		225		190	ns
			4.5 V		18	30		45		38	
			6 V		17	26		38		32	
$t_t$		Y	2 V		28	60		90		75	ns
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range,  $C_L = 150$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC}$	$T_A = 25^\circ\text{C}$			SN54HC241		SN74HC241		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2 V		50	165		245		210	ns
			4.5 V		16	33		49		42	
			6 V		14	28		42		35	
$t_{en}$	$\overline{OE}$ or OE	Y	2 V		100	200		300		250	ns
			4.5 V		20	40		60		50	
			6 V		17	34		51		43	
$t_t$		Y	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	

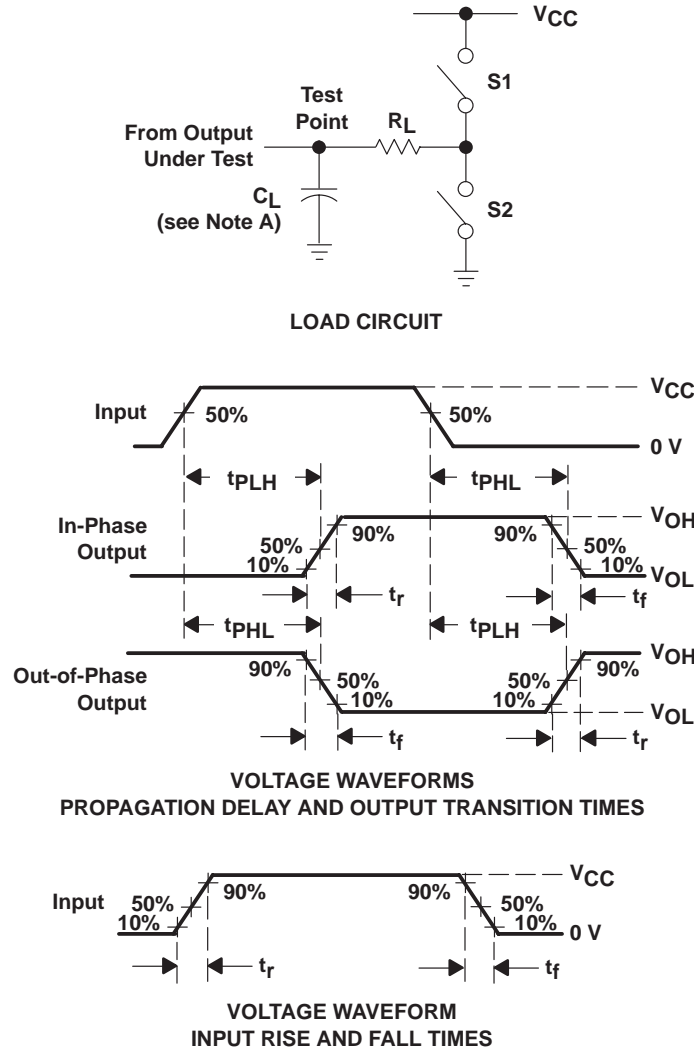
operating characteristics,  $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
$C_{pd}$	Power dissipation capacitance per buffer/driver	No load	35	pF

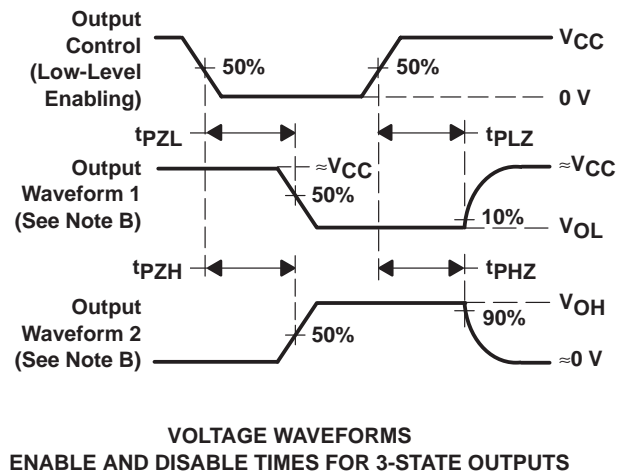
# SN54HC241, SN74HC241 OCTAL BUFFERS AND LINE DRIVERS WITH 3-STATE OUTPUTS

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## PARAMETER MEASUREMENT INFORMATION



PARAMETER	R <sub>L</sub>	C <sub>L</sub>	S1	S2
t <sub>en</sub>	1 kΩ	50 pF or 150 pF	Open	Closed
			Closed	Open
t <sub>dis</sub>	1 kΩ	50 pF	Open	Closed
			Closed	Open
t <sub>pd</sub> or t <sub>t</sub>	--	50 pF or 150 pF	Open	Open



- NOTES:
- A. C<sub>L</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> = 6 ns, t<sub>f</sub> = 6 ns.
  - D. The outputs are measured one at a time with one input transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
JM38510/65704BRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN54HC241J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC241DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC241NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC241NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241PWT	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC241PWTE4	ACTIVE	TSSOP	PW	20	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54HC241FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC241J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

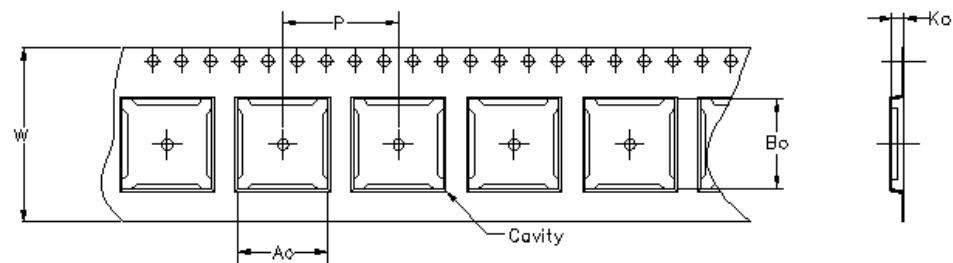
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

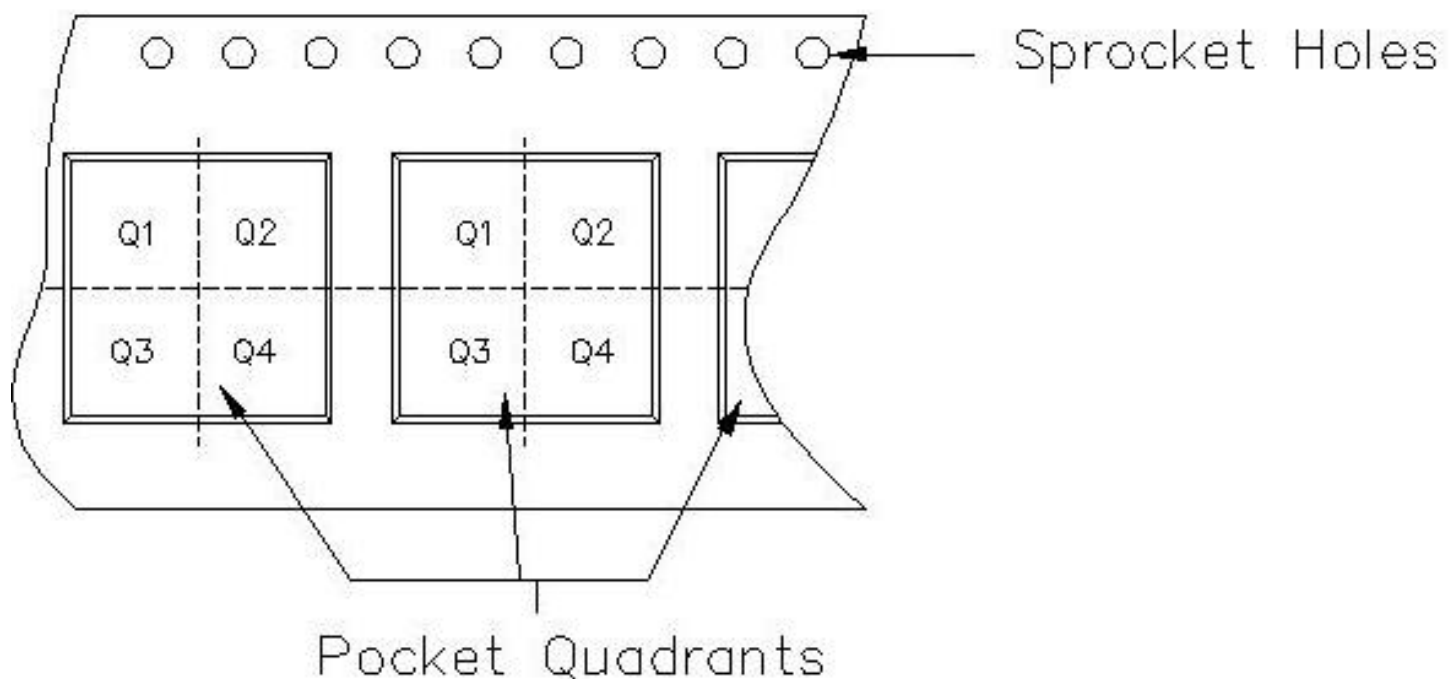
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Carrier tape design is defined largely by the component length, width, and thickness.

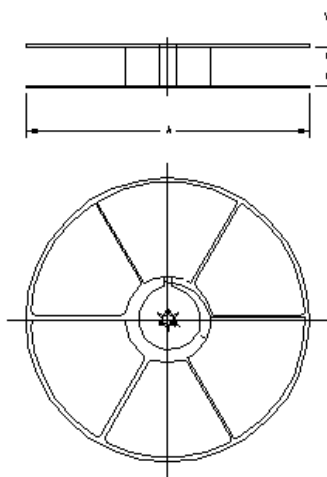
$A_0$ = Dimension designed to accommodate the component width.
$B_0$ = Dimension designed to accommodate the component length.
$K_0$ = Dimension designed to accommodate the component thickness.
$W$ = Overall width of the carrier tape.
$P$ = Pitch between successive cavity centers.



## TAPE AND REEL INFORMATION

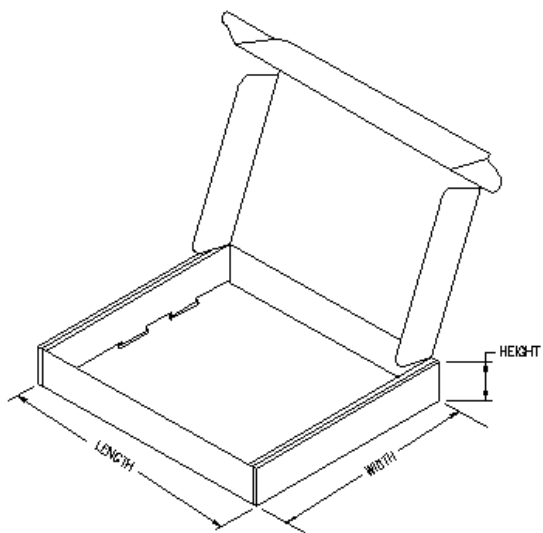


Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC241DWR	DW	20	MLA	330	24	10.8	13.0	2.7	12	24	Q1
SN74HC241NSR	NS	20	MLA	330	24	8.2	13.0	2.5	12	24	Q1
SN74HC241PWR	PW	20	MLA	330	16	6.95	7.1	1.6	8	16	Q1



## TAPE AND REEL BOX INFORMATION

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74HC241DWR	DW	20	MLA	333.2	333.2	31.75
SN74HC241NSR	NS	20	MLA	333.2	333.2	31.75
SN74HC241PWR	PW	20	MLA	342.9	336.6	28.58



J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



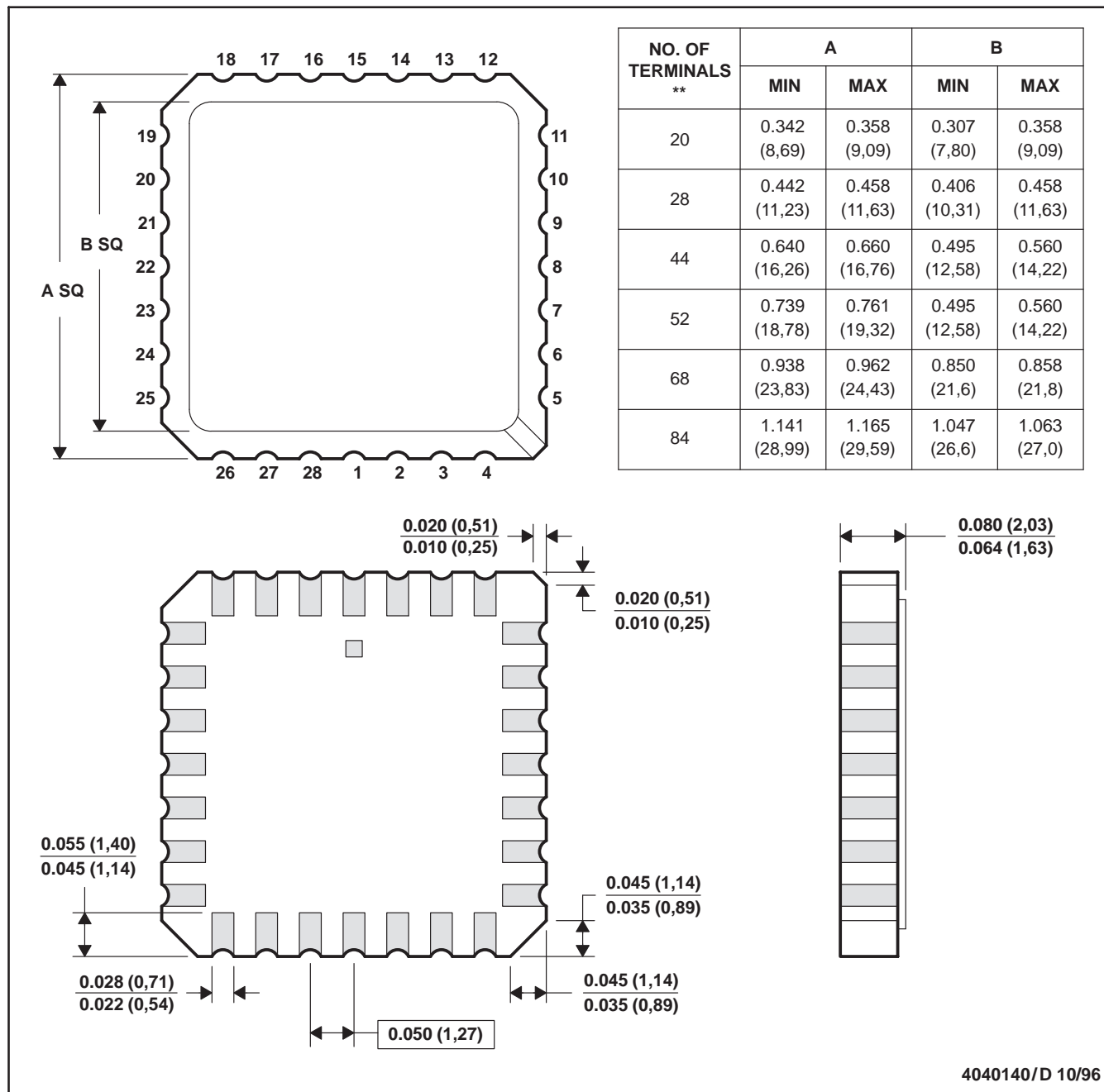
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package can be hermetically sealed with a metal lid.
  - The terminals are gold plated.
  - Falls within JEDEC MS-004

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



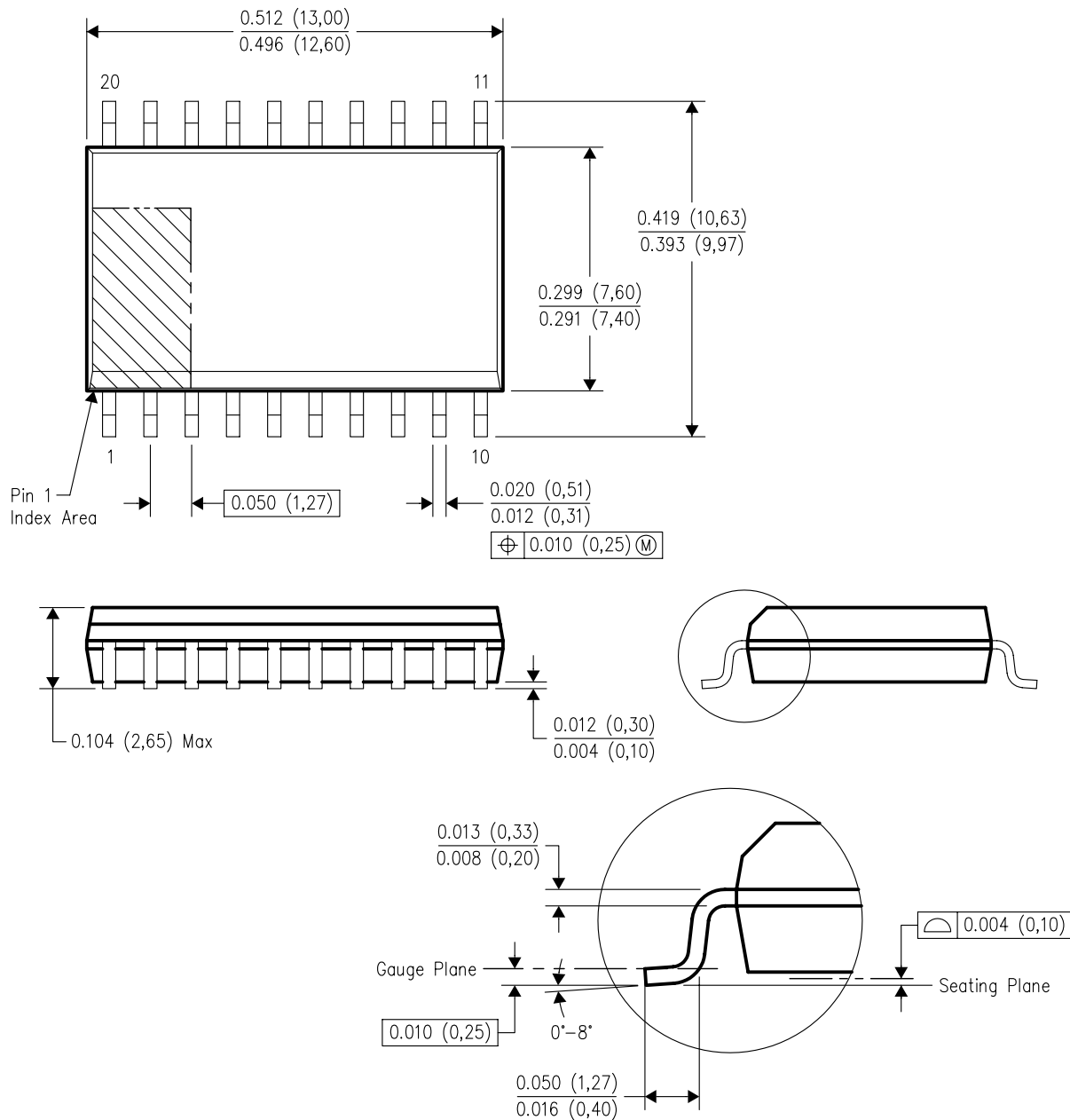
14/18 Pin Only  
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

## DW (R-PDSO-G20)

## PLASTIC SMALL-OUTLINE PACKAGE



4040000-4/F 06/2004

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

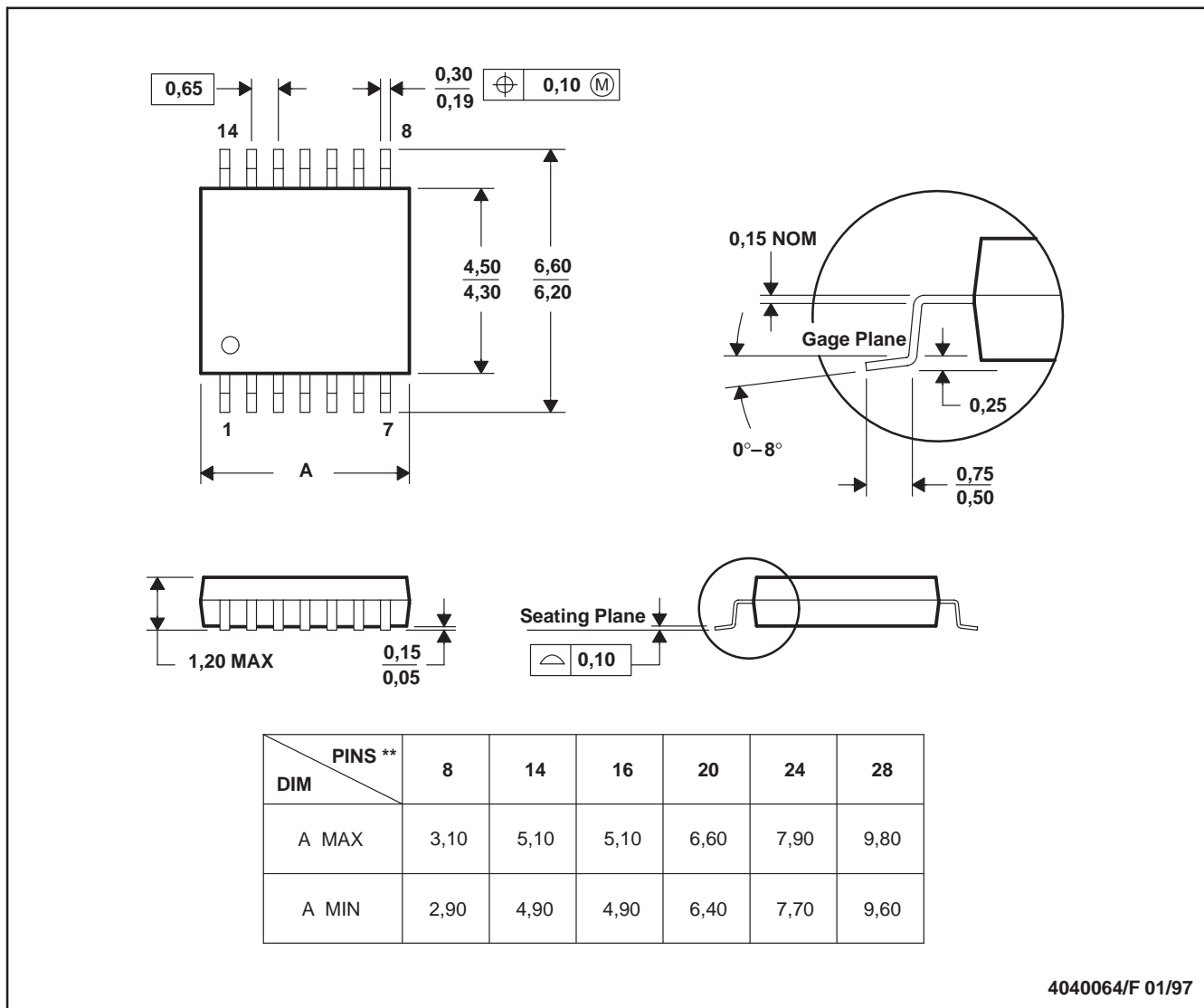


- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

## PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153



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